



COMPLEMENTARY PAIR ENHANCEMENT MODE FIELD EFFECT TRANSISTOR

Features

- Low On-Resistance
- Low Gate Threshold Voltage $V_{GS(th)} < 1V$
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Complementary Pair MOSFET
- Ultra-Small Surface Mount Package
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 2 & 3)
- Halogen and Antimony Free. "Green" Device (Note 4)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

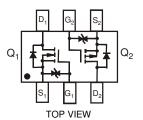
- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Terminal Connections: See Diagram
- Marking Information: See Page 7
- Ordering & Date Code Information: See Page 7
- Weight: 0.006 grams (approximate)

SOT-363









Internal Schematic

Maximum Ratings N-CHANNEL – Q₁ @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Drain Source Voltage	V _{DSS}	20	V	
Gate-Source Voltage		V _{GSS}	±8	V
Drain Current (Note 1)	$T_A = 25$ °C $T_A = 85$ °C	I _D	540 390	mA

Maximum Ratings P-CHANNEL − Q₂ @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit	
Drain Source Voltage	V _{DSS}	-20	V	
Gate-Source Voltage		V _{GSS}	±8	V
Drain Current (Note 1)	$T_A = 25$ °C $T_A = 85$ °C	I _D	-430 -310	mA

Thermal Characteristics – Total Device @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P_d	250	mW
Thermal Resistance, Junction to Ambient	$R_{ hetaJA}$	500	°C/W
Operating and Storage Temperature Range	Tj, T _{STG}	-65 to +150	°C

Notes:

- 1. Device mounted on FR-4 PCB.
- 2. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 3. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 4. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Electrical Characteristics N-CHANNEL – Q₁ @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)				•		
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 10\mu A$
Zero Gate Voltage Drain Current	I _{DSS}	_		1	μΑ	$V_{DS} = 16V, V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	_		± 1	μΑ	$V_{GS} = \pm 4.5V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.5	_	1.0	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
		_	0.4	0.55		$V_{GS} = 4.5V, I_D = 540mA$
Static Drain-Source On-Resistance	R _{DS (ON)}	_	0.5	0.70	Ω	$V_{GS} = 2.5V, I_D = 500mA$
		_	0.7	0.90		$V_{GS} = 1.8V, I_D = 350mA$
Forward Transfer Admittance	Y _{fs}	200		_	mS	$V_{DS} = 10V, I_D = 0.2A$
Diode Forward Voltage (Note 5)	V_{SD}	0.5	_	1.2	V	$V_{GS} = 0V, I_{S} = 115mA$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	_	_	150	pF	
Output Capacitance	Coss	_	_	25	pF	V _{DS} = 16V, V _{GS} = 0V - f = 1.0MHz
Reverse Transfer Capacitance	C _{rss}	_	_	20	pF	71 - 1.01VII 12

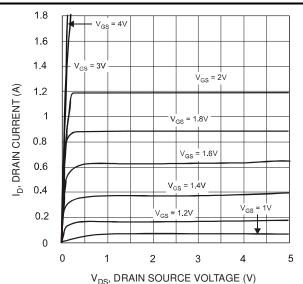
Electrical Characteristics P-CHANNEL – Q₂ @T_A = 25°C unless otherwise specified

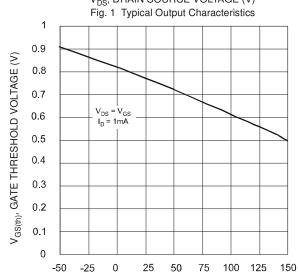
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 5)					•	•		
Drain-Source Breakdown Voltage	BV _{DSS}	-20	_	_	V	$V_{GS} = 0V, I_D = -250 \mu A$		
Zero Gate Voltage Drain Current	I _{DSS}	_	_	-1.0	μΑ	$V_{DS} = -20V, V_{GS} = 0V$		
Gate-Source Leakage	I _{GSS}	_	_	± 1.0	μΑ	$V_{GS}=\pm 4.5V,V_{DS}=0V$		
ON CHARACTERISTICS (Note 5)								
Gate Threshold Voltage	V _{GS(th)}	-0.5	_	-1.0	V	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		
Static Drain-Source On-Resistance	R _{DS (ON)}	_	0.7 1.1 1.7	0.9 1.4 2.0	Ω	$V_{GS} = -4.5V$, $I_{D} = -430 mA$ $V_{GS} = -2.5V$, $I_{D} = -300 mA$ $V_{GS} = -1.8V$, $I_{D} = -150 mA$		
Forward Transfer Admittance	Y _{fs}	200	_	_	mS	$V_{DS} = 10V, I_D = 0.2A$		
Diode Forward Voltage (Note 5)	V _{SD}	-0.5	_	-1.2	V	$V_{GS} = 0V, I_{S} = -115mA$		
DYNAMIC CHARACTERISTICS								
Input Capacitance	C _{iss}	_	_	175	pF	V _{DS} = -16V, V _{GS} = 0V f = 1.0MHz		
Output Capacitance	C _{oss}		_	30	pF			
Reverse Transfer Capacitance	C _{rss}	_	_	20	pF	I = I.UIVIDZ		

Notes: 5. Short duration pulse test used to minimize self-heating effect.

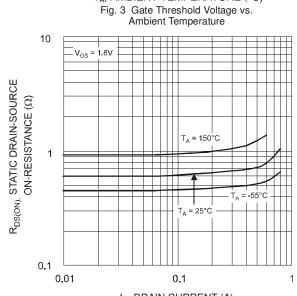


Q_{1,} N-CHANNEL

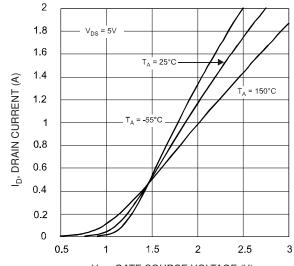




T_A, AMBIENT TEMPERATURE (°C)



I_D, DRAIN CURRENT (A)
Fig. 5 Static Drain-Source On-Resistance vs.
Drain Current



V_{GS}, GATE SOURCE VOLTAGE (V) Fig. 2 Typical Transfer Characteristics

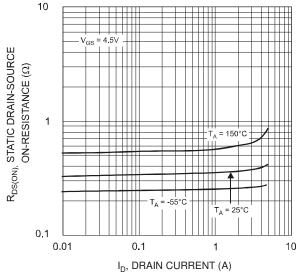
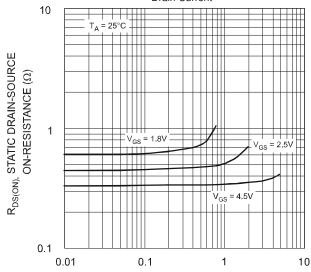


Fig. 4 Static Drain-Source On-Resistance vs.

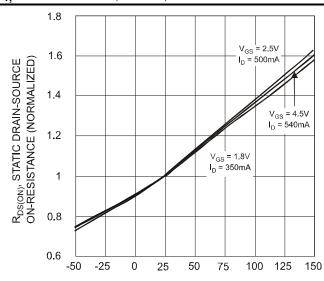
Drain Current



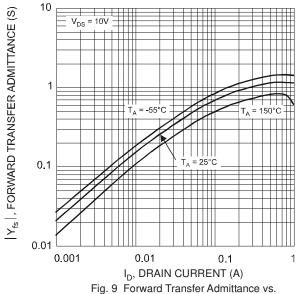
I_D, DRAIN-SOURCE CURRENT (A)
Fig. 6 Static Drain-Source On-Resistance vs.
Drain-Source Current vs. Gate Source Voltage



Q_{1.} N-CHANNEL (continued)



TA, AMBIENT TEMPERATURE (°C) Fig. 7 Static Drain-Source On-State Resistance vs. Ambient Temperature



Drain Current

1 V_{GS} = 0V I_{DR}, REVERSE DRAIN CURRENT (A) 0.1 0.01 0.001 0.2 0.4 0.6 0.8 1

V_{SD}, DRAIN-SOURCE VOLTAGE (V) Fig. 8 Reverse Drain Current vs. Source-Drain Voltage

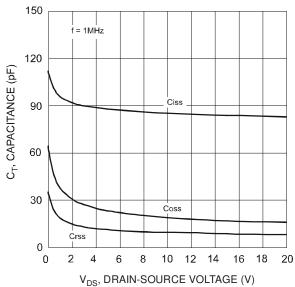


Fig. 10 Typical Capacitance



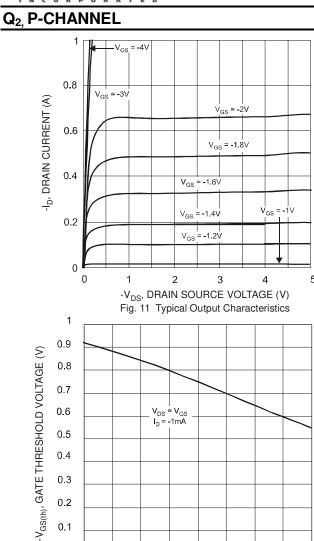
0.3 0.2 0.1 0

-25

-50

0

25



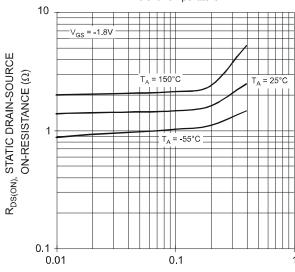
T_A, AMBIENT TEMPERATURE (°C) Fig. 13 Gate Threshold Voltage vs. **Ambient Temperature**

50

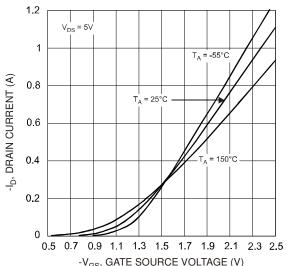
75

100 125

150



 $-I_D$, DRAIN-SOURCE CURRENT (A) Fig. 15 Static Drain-Source On-Resistance vs. **Drain Current**



 $-V_{GS}$, GATE SOURCE VOLTAGE (V) Fig. 12 Typical Transfer Characteristics

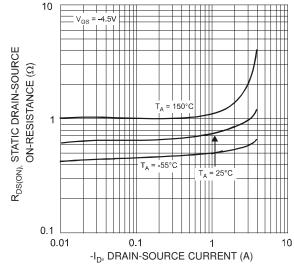
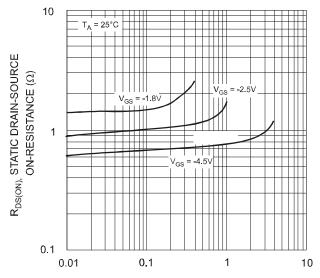


Fig. 14 Static Drain-Source On-Resistance vs. **Drain Current**



-I_D, DRAIN-SOURCE CURRENT (A) Fig. 16 Static Drain-Source On-Resistance vs. Drain-Source Current vs. Gate Source Voltage



Q_{2.} P-CHANNEL (continued)

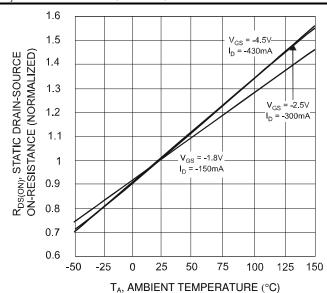


Fig. 17 Static Drain-Source On-State Resistance vs. Ambient Temperature

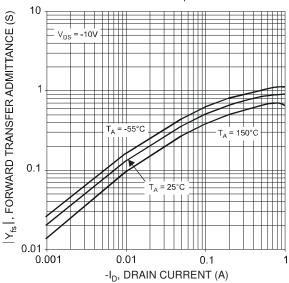


Fig. 19 Forward Transfer Admittance vs. Drain Current

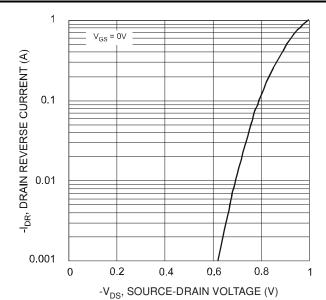


Fig. 18 Reverse Drain Current vs. Source-Drain Voltage

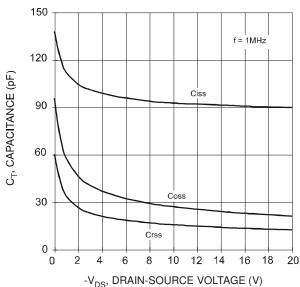


Fig. 20 Typical Capacitance

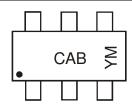


Ordering Information (Note 6)

Part Number	Case	Packaging
DMC2004DWK-7	SOT-363	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



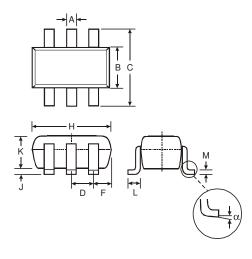
CAB = Marking Code YM = Date Code Marking Y = Year ex: U = 2007 M = Month ex: 9 = September

Date Code Key

Year	20	07	20	08	20	09	20	10	20	11	20	12
Code	l	J	\	1	V	٧)	(\	1	Z	<u>7</u>
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Package Outline Dimensions

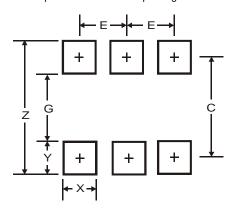
Please see http://www.diodes.com/package-outlines.html for the latest version.



SOT-363						
Dim	Min	Max				
Α	0.10	0.30				
В	1.15	1.35				
С	2.00	2.20				
D	0.65 Nominal					
F	0.30	0.40				
Н	1.80	2.20				
J	_	0.10				
K	0.90	1.00				
L	0.25	0.40				
М	0.10	0.25				
α	0°	8°				
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Υ	0.6
С	1.9
E	0.65



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